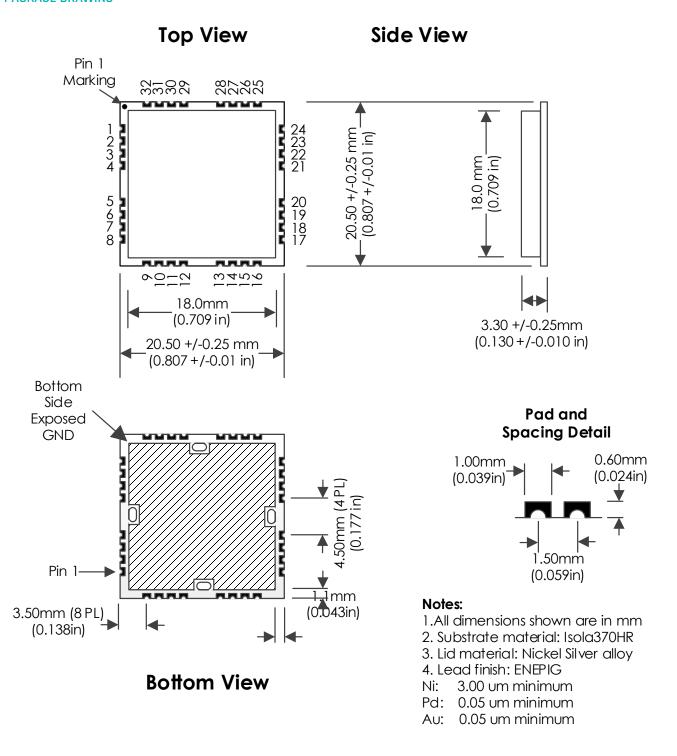
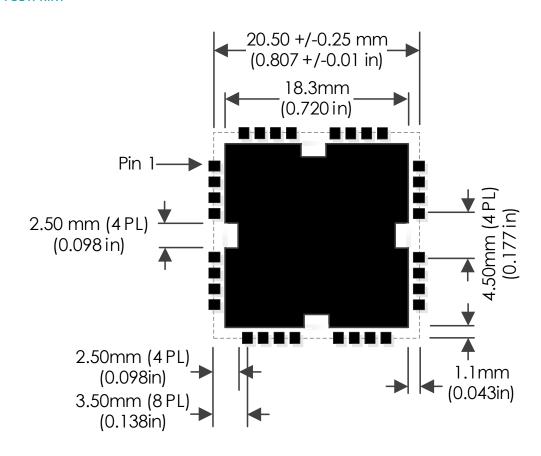


PACKAGE DRAWING

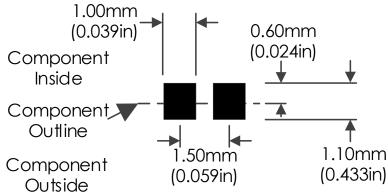




RECOMMENDED FOOTPRINT



Pad and Spacing Detail





RECOMMENDED ASSEMBLY PROCEDURE

It is recommended to attach the bottom side ground pad to the printed circuit board using a highly conductive silver epoxy and then hand solder the 20 pins along the part's perimeter to their intended printed circuit board pads using lead-free solder.

The recommended silver epoxy is MG Chemicals part 8331S and the recommended assembly thickness is 3 to 5 mils.

If the device is to be attached (both the ground pad and perimeter pins) to the circuit board using a typical lead-free solder reflow process reaching temperatures of 260C, the excessive temperature can cause internal parts to the filter bank to reflow and result in damage to the device. If a solder reflow process must be used, it is recommended to use a lower temperature leaded solder profile, typically 225C maximum.

PACKAGE NAMING CONVENTION*

Name Segment	Meaning
QFN	Quad Flat No-Lead
150	Pitch = 1.50 mm
2050	Body Width = 20.50 mm
2050	Body Length = 20.50 mm
330	Height = 3.30 mm
32	Pin Quantity

^{*} Based on the IPC-7351B naming convention.

REVISION HISTORY

Date	Revision	Notes
April 8, 2020	1	Initial Release.
August 13, 2024	2	Changed to Mercury branding. No content changes.

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